

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT														
NATURE OF CONVEYANCE:	ASSIGNMENT														
CONVEYING PARTY DATA															
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>CHRISTOPHER J. JEZEWSKI</td> <td>01/21/2014</td> </tr> <tr> <td>JASMEET S. CHAWLA</td> <td>01/21/2014</td> </tr> <tr> <td>KANWAL JIT SINGH</td> <td>01/21/2014</td> </tr> <tr> <td>ALAN M. MYERS</td> <td>01/21/2014</td> </tr> <tr> <td>ELLIOT N. TAN</td> <td>01/24/2014</td> </tr> <tr> <td>RICHARD E. SCHENKER</td> <td>01/21/2014</td> </tr> </tbody> </table>		Name	Execution Date	CHRISTOPHER J. JEZEWSKI	01/21/2014	JASMEET S. CHAWLA	01/21/2014	KANWAL JIT SINGH	01/21/2014	ALAN M. MYERS	01/21/2014	ELLIOT N. TAN	01/24/2014	RICHARD E. SCHENKER	01/21/2014
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RICHARD E. SCHENKER	01/21/2014														
RECEIVING PARTY DATA															
Name:	INTEL CORPORATION														
Street Address:	2200 MISSION COLLEGE BOULEVARD														
City:	SANTA CLARA														
State/Country:	CALIFORNIA														
Postal Code:	95054														
PROPERTY NUMBERS Total: 1															
<table border="1"> <thead> <tr> <th>Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>14163323</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	14163323										
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Application Number:	14163323														
CORRESPONDENCE DATA															
Fax Number:	(612)332-8352														
Email:	ILOH-formals@cpaglobal.com														
<i>Correspondence will be sent via US Mail when the email attempt is unsuccessful.</i>															
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ATTORNEY DOCKET NUMBER:	P61795														
NAME OF SUBMITTER:	MAYURI SAXENA														

PATENT

Signature:	/Mayuri Saxena/
Date:	02/24/2014
Total Attachments: 2 source=P61795_ASSIGNMENT#page1.tif source=P61795_ASSIGNMENT#page2.tif	

ASSIGNMENT

In consideration of good and valuable consideration, the receipt of which is hereby acknowledged, we, the undersigned inventor(s):

CHRISTOPHER J. JEZEWSKI; JASMEET S. CHAWLA; KANWAL JIT SINGH; ALAN M. MYERS; ELLIOT N. TAN; RICHARD E. SCHENKER

hereby sell, assign, and transfer to:

Intel Corporation

a corporation of Delaware, having a principal place of business at 2200 Mission College Boulevard, Santa Clara, California, 95054 USA ("Assignee"), and its successors, assigns, and legal representatives, the entire right, title, and interest for the United States and all other countries, in and to any and all inventions and improvements that are disclosed in the application for the patent entitled:

METHODS FOR FORMING INTERCONNECT LAYERS HAVING TIGHT PITCH INTERCONNECT STRUCTURES

(I hereby authorize and request any attorney having appropriate authority from the assignee to insert on the designated lines below, the filing date and application number of said application when known.)

which was filed on January 24, 2014 as
United States of America Application Number 14/163,323 and
COUNTRY or International Office

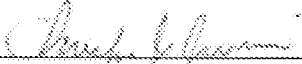
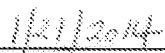
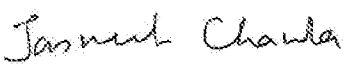
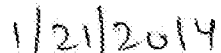
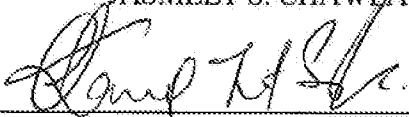


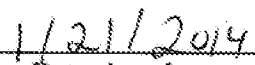
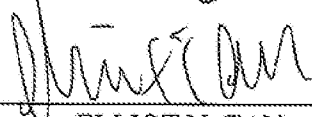
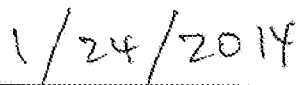
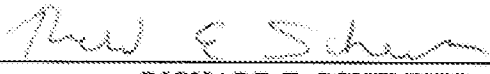
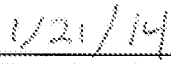
which has been executed by the undersigned prior hereto or concurrently herewith on the date(s) indicated below,

and in and to said application and all Additional Applications, and all other patent applications that have been or shall be filed in the United States and all other countries and international filing offices on any of said inventions and improvements; and in and to all original and reissued patents that have been or shall be issued in the United States and all other countries and international filing offices on said inventions and improvements; and in and to all rights of priority resulting from the filing of said applications; as used herein "Additional Applications" includes but is not limited to design, utility, utility model, divisional, continuing, continuation-in-part, substitute, renewal, reissue, and national phase applications on said inventions and improvements;

and agree that said Assignee may apply for and receive a patent or patents for said inventions and improvements in its own name; and that, when requested, without charge to, but at the expense of, said Assignee, its successors, assigns, and legal representatives, to carry out in good faith the intent and purpose of this Assignment, the undersigned will execute all Additional Applications, and all other patent applications on any and all said inventions and improvements; execute all rightful oaths, assignments, powers of attorney, and other papers; communicate to said Assignee, its successors,

assigns, and legal representatives all facts known to the undersigned relating to said inventions and improvements and the history thereof; and generally assist said Assignee, its successors, assigns, or legal representatives in securing and maintaining proper patent protection for said inventions and improvements and for vesting title to said inventions and improvements, and all applications for patents and all patents on said improvements, in said Assignee, its successors, assigns, and legal representatives; and

covenant with said Assignee, its successors, assigns, and legal representatives that no assignment, grant, mortgage, license, or other agreement affecting the rights and property herein conveyed has been made to others by the undersigned, and that full right to convey the same as herein expressed is possessed by the undersigned.

 _____ CHRISTOPHER J. JEZEWSKI	 _____ Date signed
 _____ JASMEET S. CHAWLA	 _____ Date signed
 _____ KANWAL JIT SINGH	 _____ Date signed
 _____ ALAN M. MYERS	 _____ Date signed
 _____ ELLIOT N. TAN	 _____ Date signed
 _____ RICHARD E. SCHENKER	 _____ Date signed